

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4569747

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
I-Fan Chang	08/24/2017
Yen-Liang Wu	08/24/2017
Wen-Tsung Chang	08/24/2017
Jui-Ming Yang	08/24/2017
Jie-Ning Yang	08/24/2017
Chi-Ju Lee	08/24/2017
Chun-Ting Chiang	08/24/2017
Bo-Yu Su	08/24/2017
Chih-Wei Lin	08/24/2017
Dien-Yang Lu	08/24/2017
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15688852
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4:	NEW TAIPEI CITY, TAIWAN
ATTORNEY DOCKET NUMBER:	NAUP3103USA
NAME OF SUBMITTER:	SIBYL YU

SIGNATURE:	/SIBYL YU/
DATE SIGNED:	08/28/2017
Total Attachments: 20 source=2942025#page1.tif source=2942025#page2.tif source=2942025#page3.tif source=2942025#page4.tif source=2942025#page5.tif source=2942025#page6.tif source=2942025#page7.tif source=2942025#page8.tif source=2942025#page9.tif source=2942025#page10.tif source=2942025#page11.tif source=2942025#page12.tif source=2942025#page13.tif source=2942025#page14.tif source=2942025#page15.tif source=2942025#page16.tif source=2942025#page17.tif source=2942025#page18.tif source=2942025#page19.tif source=2942025#page20.tif	

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

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representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this AUG 24 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **I-Fan Chang**

Date: **AUG 24 2017**

Signature: I-Fan Chang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yen-Liang Wu**

Date: **AUG 24 2017**

Signature:

Yen - Liang Wu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Wen-Tsung Chang**

Date: **AUG 24 2017**

Signature: Wen-Tsung Chang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Jui-Ming Yang**

Date: **AUG 24 2017**

Signature: Jui-Ming Yang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Jie-Ning Yang**

Date: **AUG 24 2017**

Signature:

Jie-Ning Yang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chi-Ju Lee**

Date: **AUG 24 2017**

Signature: Chi-Ju Lee

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chun-Ting Chiang**

Date: **AUG 24 2017**

Signature: Chun-Ting Chiang

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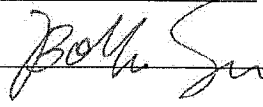
LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Bo-Yu Su**

Date:

AUG 24 2017

Signature:



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Inventor: Chih-Wei Lin

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Signature: Chih-Wei Lin

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Inventor: Dien-Yang Lu

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